ABSTRACT

A semiconductor package that can accommodate a larger semiconductor chip while keeping the foot print area afforded to a conventional semiconductor package. The semiconductor package of the invention also has an improved locking strength between a chip paddle and an encapsulation material. Additionally, the semiconductor chip of the invention exhibits an improved heat radiation of the semiconductor chip over conventional semiconductor packages. The package of the invention comprises a semiconductor chip having a plurality of bond pads on its upper surface; a chip paddle bonded to the bottom surface of the semiconductor chip by an adhesive; a plurality of internal leads, each having an etched part at the end facing the chip paddle, which are radially formed at regular intervals along the circumference of the chip paddle; conductive wires for electrically connecting the bond pads of the semiconductor chip to the internal leads; and a package body in which the semiconductor chip, the conductive wires, the chip paddle and the internal leads are encapsulated by an encapsulation material while the chip paddle and the internal leads are externally exposed at their side surfaces and bottom surfaces.